

- Ultra Low On-Resistance
- Surface Mount (IRFR3910)
- Straight Lead (IRFU3910)
- Advanced Process Technology
- Fast Switching
- Fully Avalanche Rated
- Lead-Free

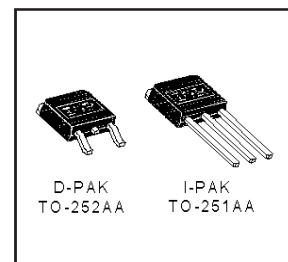
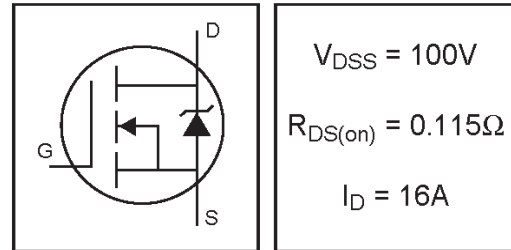
### Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve the lowest possible on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient device for use in a wide variety of applications.

The D-PAK is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. The straight lead version (IRFU series) is for through-hole mounting applications. Power dissipation levels up to 1.5 watts are possible in typical surface mount applications.

# IRFR3910PbF IRFU3910PbF

HEXFET® Power MOSFET



### Absolute Maximum Ratings

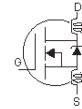
|                                 | Parameter                                       | Max.         | Units |
|---------------------------------|---|--------------|-------|
| $I_D @ T_C = 25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10\text{V}$ | 16           | A     |
| $I_D @ T_C = 100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10\text{V}$ | 12           |       |
| $I_{DM}$                        | Pulsed Drain Current ①⑥                         | 60           |       |
| $P_D @ T_C = 25^\circ\text{C}$  | Power Dissipation                               | 79           | W     |
|                                 | Linear Derating Factor                          | 0.53         | W/°C  |
| $V_{GS}$                        | Gate-to-Source Voltage                          | $\pm 20$     | V     |
| $E_{AS}$                        | Single Pulse Avalanche Energy ②⑥                | 150          | mJ    |
| $I_{AR}$                        | Avalanche Current ①⑥                            | 9.0          | A     |
| $E_{AR}$                        | Repetitive Avalanche Energy ①⑥                  | 7.9          | mJ    |
| $dv/dt$                         | Peak Diode Recovery $dv/dt$ ③                   | 5.0          | V/ns  |
| $T_J$                           | Operating Junction and                          | -55 to + 175 | °C    |
| $T_{STG}$                       | Storage Temperature Range                       |              |       |
|                                 | Soldering Temperature, for 10 seconds           |              |       |

### Thermal Resistance

|                 | Parameter                          | Typ. | Max. | Units |
|-----------------|------------------------------------|------|------|-------|
| $R_{\theta JC}$ | Junction-to-Case                   | ---  | 1.9  | °C/W  |
| $R_{\theta JA}$ | Junction-to-Ambient (PCB mount) ** | ---  | 50   |       |
| $R_{\theta JA}$ | Junction-to-Ambient                | ---  | 110  |       |

## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

|                                 | Parameter                            | Min. | Typ. | Max.  | Units   | Conditions  |
|---------------------------------|--------------------------------------|------|------|-------|---------|---|
| $V_{(BR)DSS}$                   | Drain-to-Source Breakdown Voltage    | 100  | —    | —     | V       | $V_{GS} = 0V, I_D = 250\mu A$   |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient  | —    | 0.12 | —     | V/°C    | Reference to $25^\circ\text{C}$ , $I_D = 1mA$                                 |
| $R_{DS(on)}$                    | Static Drain-to-Source On-Resistance | —    | —    | 0.115 | —       | $V_{GS} = 10V, I_D = 10A$ ④   |
| $V_{GS(th)}$                    | Gate Threshold Voltage               | 2.0  | —    | 4.0   | V       | $V_{DS} = V_{GS}, I_D = 250\mu A$   |
| $g_{fs}$                        | Forward Transconductance             | 6.4  | —    | —     | S       | $V_{DS} = 50V, I_D = 9.0A$ ⑥  |
| $I_{DSS}$                       | Drain-to-Source Leakage Current      | —    | —    | 25    | $\mu A$ | $V_{DS} = 100V, V_{GS} = 0V$  |
|                                 |                                      | —    | —    | 250   |         | $V_{DS} = 80V, V_{GS} = 0V, T_J = 150^\circ\text{C}$                          |
| $I_{GSS}$                       | Gate-to-Source Forward Leakage       | —    | —    | 100   | nA      | $V_{GS} = 20V$  |
|                                 | Gate-to-Source Reverse Leakage       | —    | —    | -100  |         | $V_{GS} = -20V$   |
| $Q_g$                           | Total Gate Charge                    | —    | —    | 44    | nC      | $I_D = 9.0A$  |
| $Q_{gs}$                        | Gate-to-Source Charge                | —    | —    | 6.2   |         | $V_{DS} = 80V$  |
| $Q_{gd}$                        | Gate-to-Drain ("Miller") Charge      | —    | —    | 21    |         | $V_{GS} = 10V$ , See Fig. 6 and 13 ④ ⑤  |
| $t_{d(on)}$                     | Turn-On Delay Time                   | —    | 6.4  | —     | ns      | $V_{DD} = 50V$  |
| $t_r$                           | Rise Time                            | —    | 27   | —     |         | $I_D = 9.0A$  |
| $t_{d(off)}$                    | Turn-Off Delay Time                  | —    | 37   | —     |         | $R_G = 12\Omega$  |
| $t_f$                           | Fall Time                            | —    | 25   | —     |         | $R_D = 5.5\Omega$ , See Fig. 10 ④ ⑥   |
| $L_D$                           | Internal Drain Inductance            | —    | 4.5  | —     | nH      | Between lead,<br>6mm (0.25in.)<br>from package<br>and center of die contact ⑤ |
| $L_S$                           | Internal Source Inductance           | —    | 7.5  | —     |         |   |
| $C_{ISS}$                       | Input Capacitance                    | —    | 640  | —     | pF      | $V_{GS} = 0V$   |
| $C_{OSS}$                       | Output Capacitance                   | —    | 160  | —     |         | $V_{DS} = 25V$  |
| $C_{RSS}$                       | Reverse Transfer Capacitance         | —    | 88   | —     |         | $f = 1.0MHz$ , See Fig. 5 ⑥   |



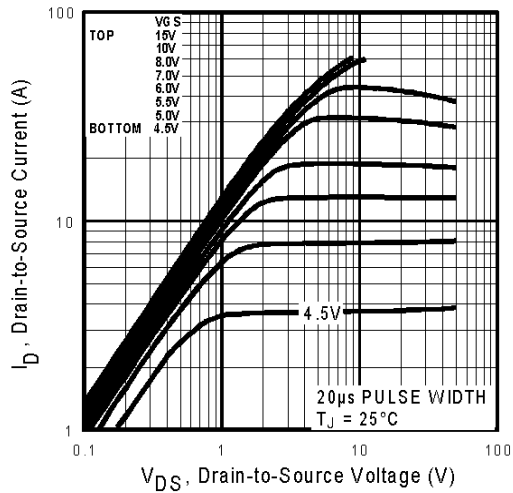
## Source-Drain Ratings and Characteristics

|          | Parameter                                 | Min.  | Typ. | Max. | Units | Conditions  |
|----------|---|---|------|------|-------|---|
| $I_S$    | Continuous Source Current<br>(Body Diode) | —   | —    | 16   | A     | MOSFET symbol<br>showing the<br>integral reverse<br>p-n junction diode. |
| $I_{SM}$ | Pulsed Source Current<br>(Body Diode) ① ⑥ | —   | —    | 60   |       |   |
| $V_{SD}$ | Diode Forward Voltage                     | —   | —    | 1.3  | V     | $T_J = 25^\circ\text{C}, I_S = 9.0A, V_{GS} = 0V$ ④                     |
| $t_{rr}$ | Reverse Recovery Time                     | —   | 130  | 190  | ns    | $T_J = 25^\circ\text{C}, I_F = 9.0A$                                    |
| $Q_{rr}$ | Reverse Recovery Charge                   | —   | 650  | 970  | nC    | $di/dt = 100A/\mu s$ ④ ⑥  |
| $t_{on}$ | Forward Turn-On Time                      | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$ ) |      |      |       |   |

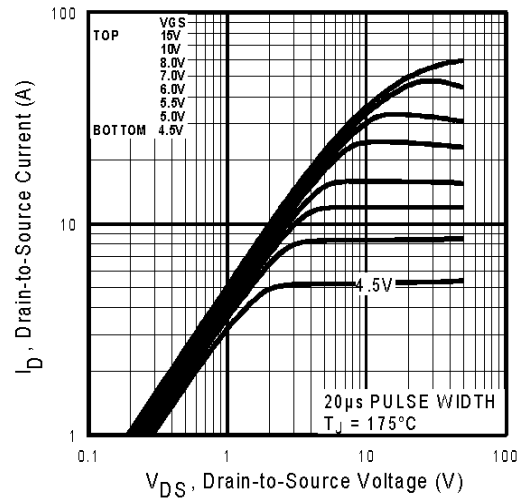
### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- ②  $V_{DD} = 25V$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 3.1mH$   
 $R_G = 25\Omega$ ,  $I_{AS} = 9.0A$ . (See Figure 12)
- ③  $I_{SD} \leq 9.0A$ ,  $di/dt \leq 520A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq 175^\circ\text{C}$
- ④ Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$
- ⑤ This is applied for I-PAK,  $L_S$  of D-PAK is measured between lead and center of die contact
- ⑥ Uses IRF530N data and test conditions

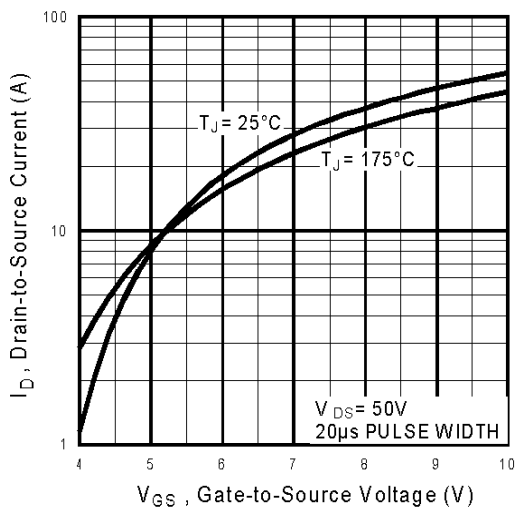
\*\* When mounted on 1" square PCB (FR-4 or G-10 Material) .  
For recommended footprint and soldering techniques refer to application note #AN-994



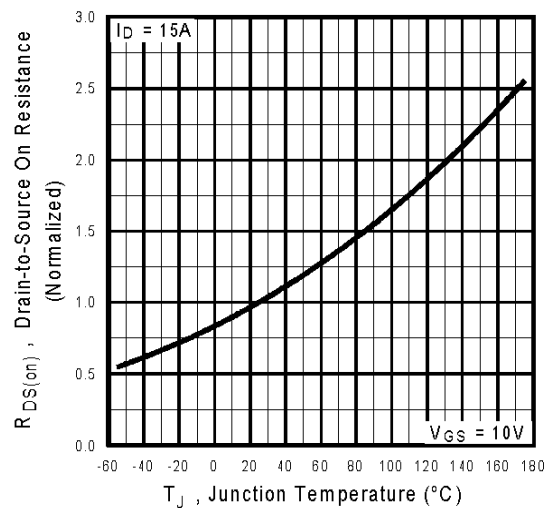
**Fig 1.** Typical Output Characteristics



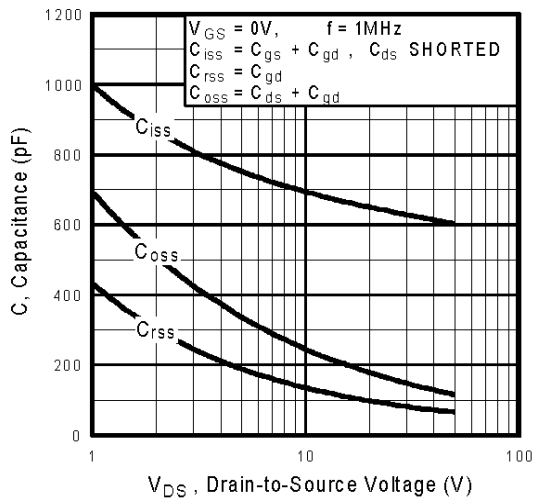
**Fig 2.** Typical Output Characteristics



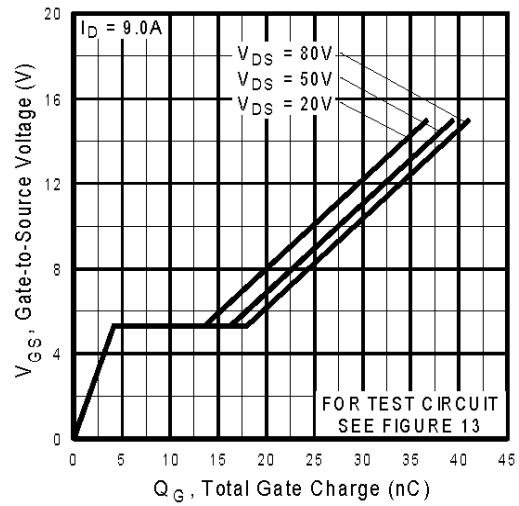
**Fig 3.** Typical Transfer Characteristics



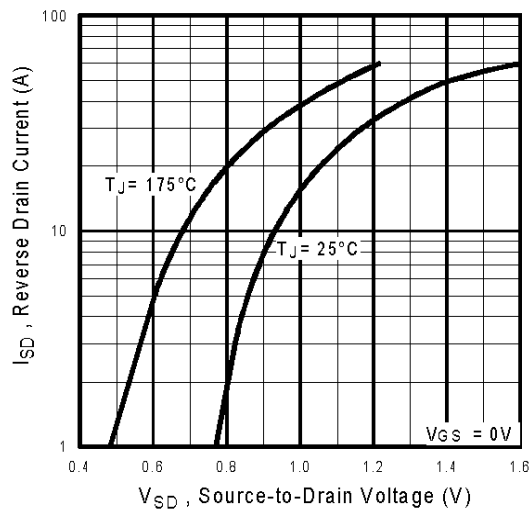
**Fig 4.** Normalized On-Resistance  
Vs. Temperature



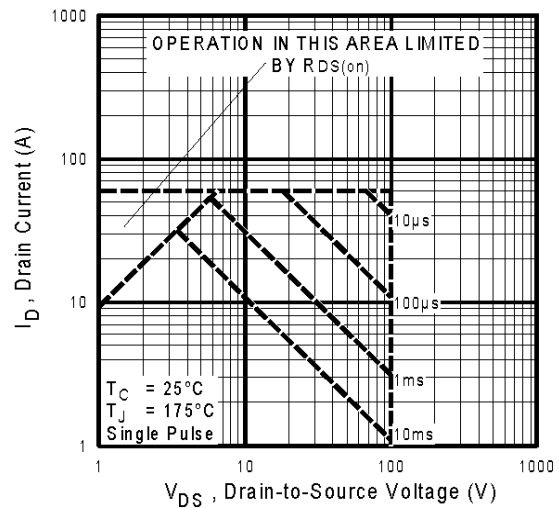
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



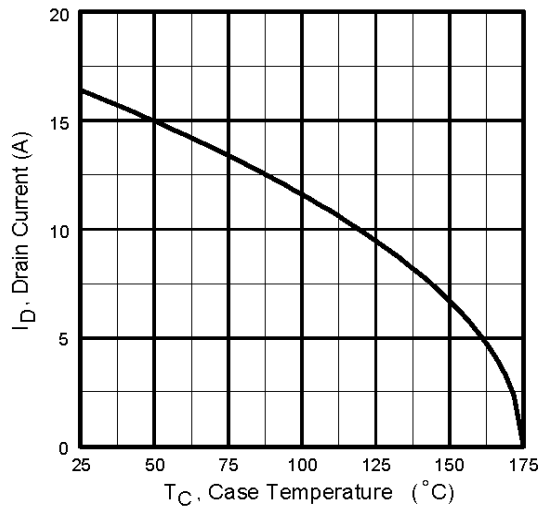
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



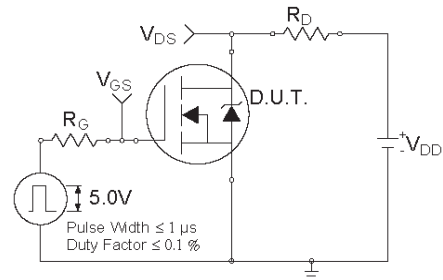
**Fig 7.** Typical Source-Drain Diode Forward Voltage



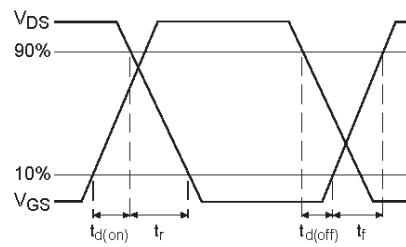
**Fig 8.** Maximum Safe Operating Area



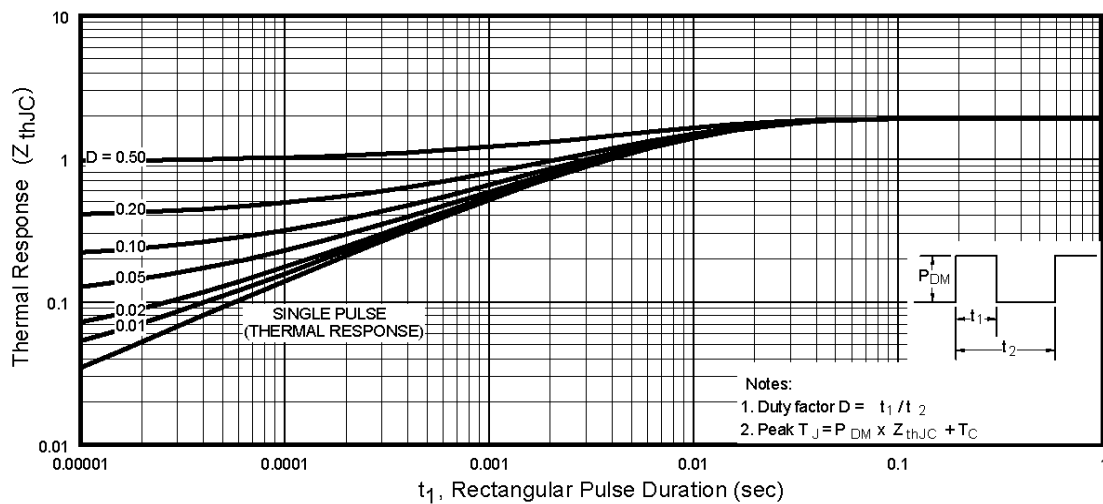
**Fig 9.** Maximum Drain Current Vs. Case Temperature



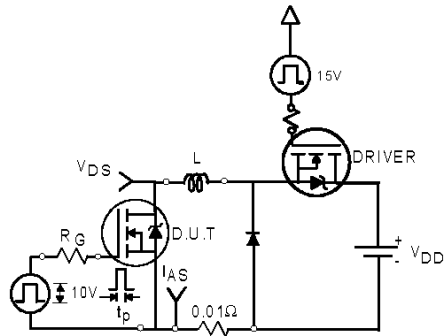
**Fig 10a.** Switching Time Test Circuit



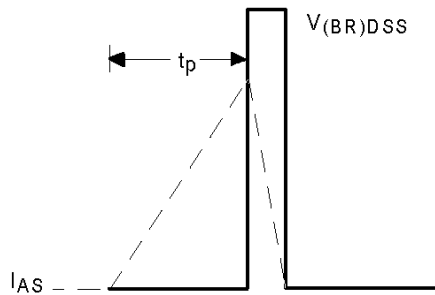
**Fig 10b.** Switching Time Waveforms



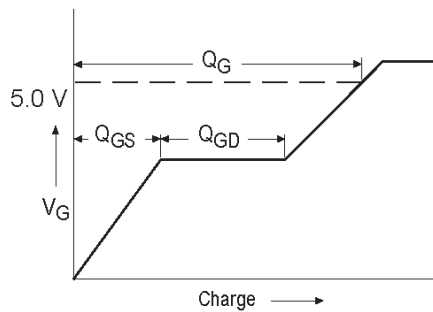
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case



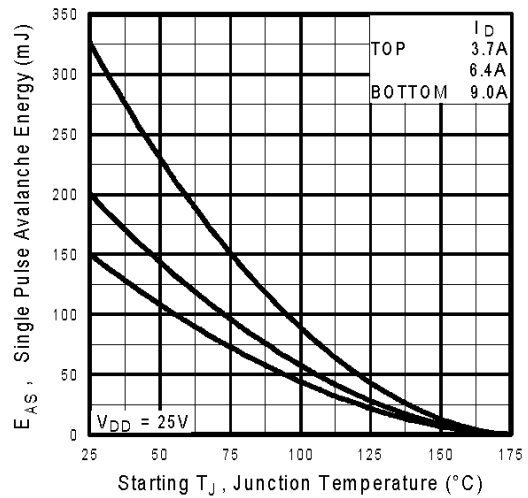
**Fig 12a.** Unclamped Inductive Test Circuit



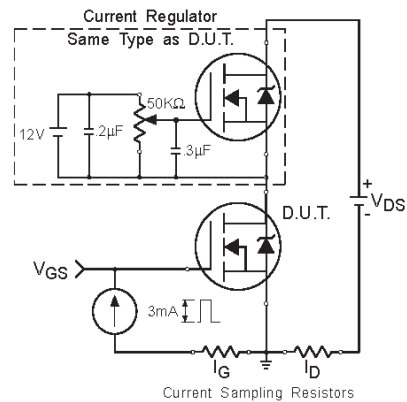
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 13a.** Basic Gate Charge Waveform

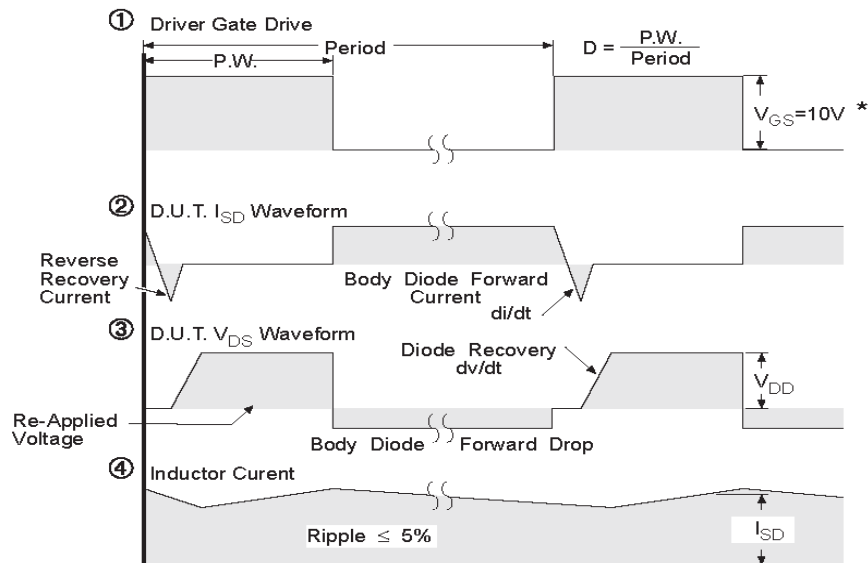
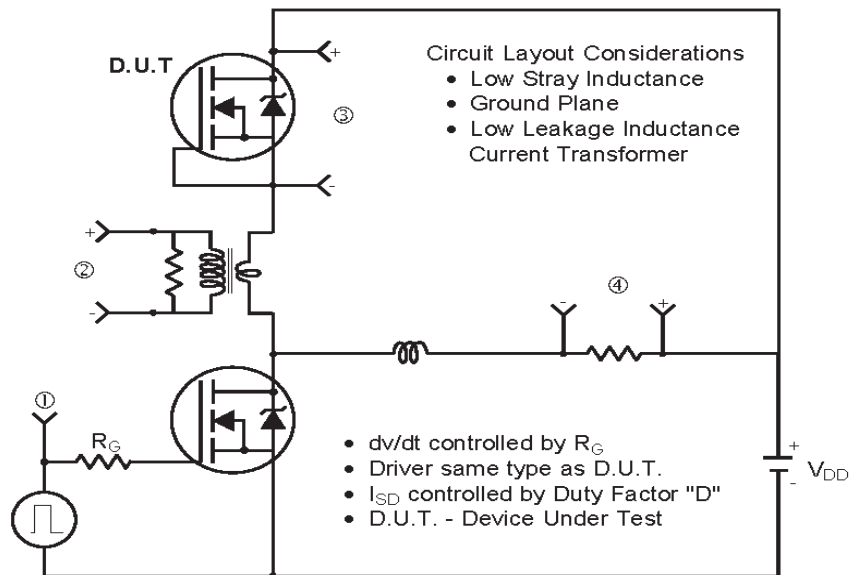


**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 13b.** Gate Charge Test Circuit

### Peak Diode Recovery dv/dt Test Circuit



\*  $V_{GS} = 5V$  for Logic Level Devices

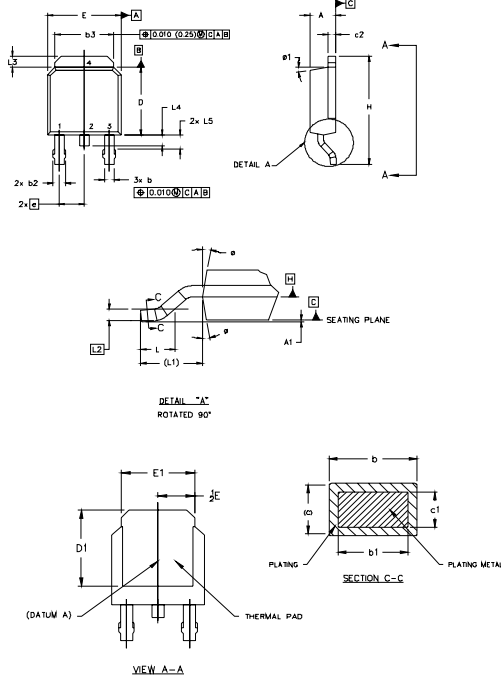
**Fig 14.** For N-Channel HEXFETS

# IRFR/U3910PbF

International  
**IR** Rectifier

## D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



- NOTES:
- 1.0 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
  - 2.0 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
  - 3.0 LEAD DIMENSION UNCONTROLLED IN L5
  - 4.0 DIMENSION D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
  - 5.0 SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 [0.127] AND .010 [0.2540] FROM THE LEAD TIP.
  - 6.0 DIMENSION D & E DO NOT INCLUDE MOLD FLASH; MOLD FLASH SHALL NOT EXCEED .002" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
  - 7.0 OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

| SYMBOL | DIMENSIONS  |       |          |       | NOTES |
|--------|-------------|-------|----------|-------|-------|
|        | MILLIMETERS |       | INCHES   |       |       |
|        | MIN.        | MAX.  | MIN.     | MAX.  |       |
| A      | 2.18        | 2.39  | .086     | .094  |       |
| A1     |             | 0.13  |          | .005  |       |
| b      | 0.64        | 0.89  | .025     | .035  | 5     |
| b1     | 0.64        | 0.79  | .025     | 0.031 | 5     |
| b2     | 0.76        | 1.14  | .030     | .045  |       |
| b3     | 4.95        | 5.46  | .195     | .215  |       |
| c      | 0.46        | 0.61  | .018     | .024  | 5     |
| c1     | 0.41        | 0.56  | .016     | .022  | 5     |
| c2     | .046        | 0.89  | .018     | .035  | 5     |
| D      | 5.97        | 6.22  | .235     | .245  | 6     |
| D1     | 5.21        | -     | .205     | -     | 4     |
| E      | 6.35        | 6.73  | .250     | .265  | 6     |
| E1     | 4.32        | -     | .170     | -     | 4     |
| e      | 2.29        |       | .090 BSC |       |       |
| H      | 9.40        | 10.41 | .370     | .410  |       |
| L      | 1.40        | 1.78  | .055     | .070  |       |
| L1     | 2.74 REF    |       | .108 REF |       |       |
| L2     | 0.051 BSC   |       | .020 BSC |       |       |
| L3     | 0.89        | 1.27  | .035     | .050  |       |
| L4     | 1.14        | 1.02  | .040     | .040  |       |
| L5     | 1.14        | 1.52  | .045     | .060  | 3     |
| ø      | 0"          | 10"   | 0"       | 10"   |       |
| ø1     | 0"          | 15"   | 0"       | 15"   |       |

### LEAD ASSIGNMENTS

#### HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

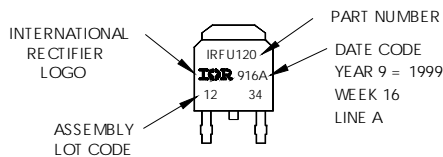
#### IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

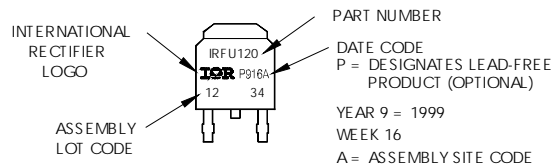
## D-Pak (TO-252AA) Part Marking Information

EXAMPLE: THIS IS AN IRFR120  
WITH ASSEMBLY  
LOT CODE 1234  
ASSEMBLED ON WW 16, 1999  
IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position  
indicates "Lead-Free"



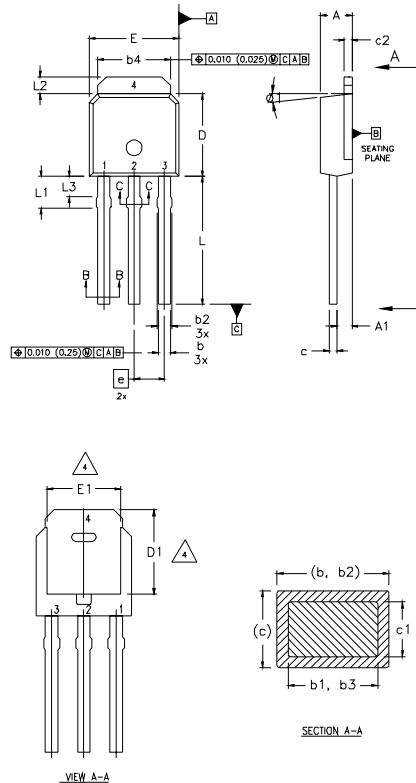
OR





## I-Pak (TO-251AA) Package Outline

Dimensions are shown in millimeters (inches)



### NOTES:

- 1 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
- 2 DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 3 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 4 THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1.
- 5 LEAD DIMENSION UNCONTROLLED IN L3.
- 6 DIMENSION b1, b3 APPLY TO BASE METAL ONLY.
- 7 OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA.
- 8 CONTROLLING DIMENSION : INCHES.

### LEAD ASSIGNMENTS

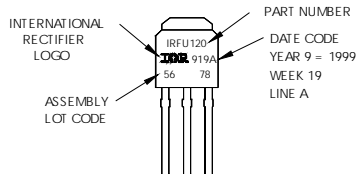
#### HEXFEE

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

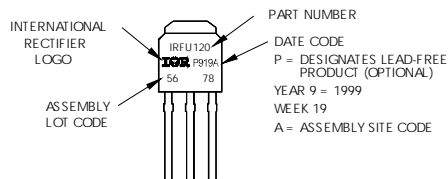
| SYMBOL | DIMENSIONS  |      |           |       | NOTES |
|--------|-------------|------|-----------|-------|-------|
|        | MILLIMETERS |      | INCHES    |       |       |
|        | MIN.        | MAX. | MIN.      | MAX.  |       |
| A      | 2.18        | 2.39 | 0.086     | .094  |       |
| A1     | 0.89        | 1.14 | 0.035     | 0.045 |       |
| b      | 0.64        | 0.89 | 0.025     | 0.035 |       |
| b1     | 0.64        | 0.79 | 0.025     | 0.031 | 4     |
| b2     | 0.76        | 1.14 | 0.030     | 0.045 |       |
| b3     | 0.76        | 1.04 | 0.030     | 0.041 |       |
| b4     | 5.00        | 5.46 | 0.195     | 0.215 | 4     |
| c      | 0.46        | 0.61 | 0.018     | 0.024 |       |
| c1     | 0.41        | 0.56 | 0.016     | 0.022 |       |
| c2     | .046        | 0.86 | 0.018     | 0.035 |       |
| D      | 5.97        | 6.22 | 0.235     | 0.245 | 3, 4  |
| D1     | 5.21        | -    | 0.205     | -     | 4     |
| E      | 6.35        | 6.73 | 0.250     | 0.265 | 3, 4  |
| E1     | 4.32        | -    | 0.170     | -     | 4     |
| e      | 2.29        |      | 0.090 BSC |       |       |
| L      | 8.89        | 9.60 | 0.350     | 0.380 |       |
| L1     | 1.91        | 2.29 | 0.075     | 0.090 |       |
| L2     | 0.89        | 1.27 | 0.035     | 0.050 | 4     |
| L3     | 1.14        | 1.52 | 0.045     | 0.060 | 5     |
| ø1     | 0"          | 15"  | 0"        | 15"   |       |

## I-Pak (TO-251AA) Part Marking Information

EXAMPLE: THIS IS AN IRFU120  
WITH ASSEMBLY  
LOT CODE 5678  
ASSEMBLED ON WW 19, 1999  
IN THE ASSEMBLY LINE "A"  
**Note:** "P" in assembly line  
position indicates "Lead-Free"



OR

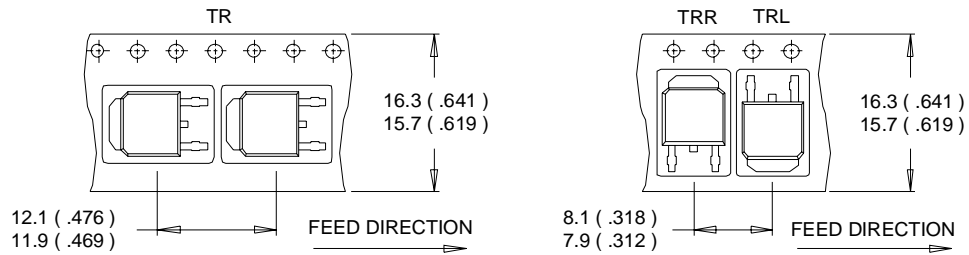


# IRFR/U3910PbF

International  
**IOR** Rectifier

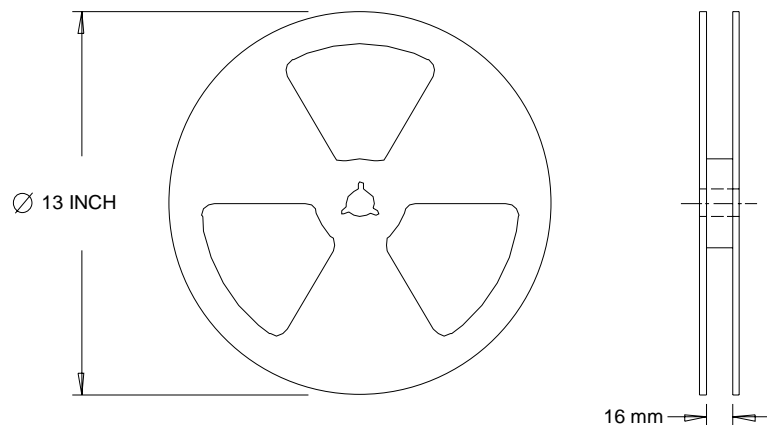
## D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



### NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS ( INCHES ).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



### NOTES :

1. OUTLINE CONFORMS TO EIA-481.

Data and specifications subject to change without notice.

International  
**IOR** Rectifier

**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105

TAC Fax: (310) 252-7903

Visit us at [www.irf.com](http://www.irf.com) for sales contact information.01/05

[www.irf.com](http://www.irf.com)

Note: For the most current drawings please refer to the IR website at:  
<http://www.irf.com/package/>

## IMPORTANT NOTICE

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenhheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

For further information on the product, technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies office ([www.infineon.com](http://www.infineon.com)).

## WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.